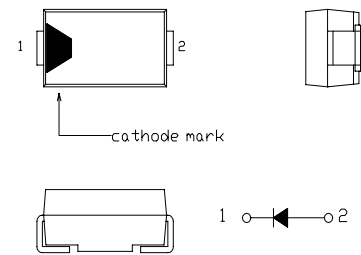


SBD Type : EC31QS03L

FEATURES

- * Miniature Size, Surface Mount Device
- * Extremely Low Forward Voltage Drop
- * Low Power Loss, High Efficiency
- * High Surge Capability
- * 30 Volts through 100Volts Types Available
- * Packaged in 12mm Tape and Reel
- * Not Rolling During Assembly

OUTLINE DRAWING



Maximum Ratings

Approx Net Weight: 0.06g

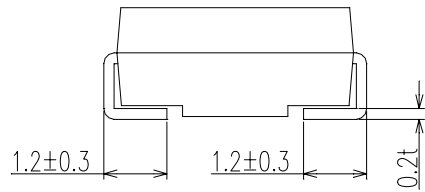
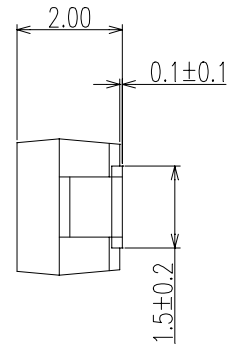
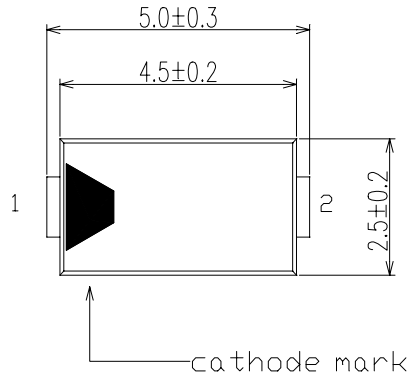
Rating	Symbol	EC31QS03L			Unit
Repetitive Peak Reverse Voltage	V_{RRM}	30			V
Average Rectified Output Current	I_o	1.3	$T_a=28^{\circ}C$ *1	50Hz Half Sine Wave Resistive Load	A
		3.0	$T_l=76^{\circ}C$		
RMS Forward Current	$I_{F(RMS)}$	4.71			A
Surge Forward Current	I_{FSM}	60	50Hz Half Sine Wave, 1cycle Non-repetitive		A
Operating Junction Temperature Range	T_{jw}	-40 to +150			$^{\circ}C$
Storage Temperature Range	T_{stg}	-40 to +150			$^{\circ}C$

Electrical • Thermal Characteristics

Characteristics		Symbol	Conditions	Min.	Typ.	Max.	Unit
Peak Reverse Current		I_{RM}	$T_j= 25^{\circ}C, V_{RM}= V_{RRM}$	-	-	3	mA
Peak Forward Voltage		V_{FM}	$T_j= 25^{\circ}C, I_{FM}= 3.0A$	-	-	0.45	V
Thermal Resistance	Junction to Ambient	$R_{th(j-a)}$	Alumina Substrate Mounted *1	-	-	108	$^{\circ}C/W$
	Junction to Lead	$R_{th(j-l)}$	-	-	-	23	

*1 Alumina Substrate Mounted (Soldering Lands=2x2mm, Both Sides)
(T_l : Lead Temperature)

EC31QS03L OUTLINE DRAWING (Dimensions in mm)



SOLDERING PAD

